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IS31LT3350 3CH Evaluation Board Guide

Description

The IS31LT3350 is a continuous mode inductive step-down converter, designed for driving a single LED or multiple series connected LEDs efficiently from a voltage source higher than the LED voltage. The chip operates from an input supply between 6V and 40V and provides an externally adjustable output current of up to 750mA. Depending upon supply voltage and external components, this can provide up to 30 watts of output power.

The IS31LT3350 includes an integrated output switch and a high-side output current sensing circuit, which uses an external resistor to set the nominal average output current.

Output current can be adjusted linearly by applying an external control signal to the ADJ pin. The ADJ pin will accept either a DC voltage or a PWM waveform. This will provide either a continuous or a gated output current. Applying a voltage of 0.2V or lower to the ADJ pin turns the output off and switches the chip into a low current standby state.

The chip is assembled in SOT23-5, SOT89-5 and SOP8 package. SOT23-5 is available for 350mA output current application; SOT89-5 and SOP8 is available for 700mA output current application.

IS31LT3350 3CH Evaluation board is used in RGB lamp or the general LED lamp.

Features

- Simple low parts count
- Internal 40V power switch
- Wide input voltage range: 6V to 40V
- Up to 750mA output current
- High efficiency (up to 95%)
- Typical 1200:1 dimming rate
- Typical 5% output current accuracy
- Single pin on/off and brightness control using DC voltage or PWM
- Up to 1MHz switching frequency
- Inherent open-circuit LED protection
- Thermal shutdown protection circuitry

Applications

- Low voltage halogen replacement LEDs
- Automotive lighting
- Low voltage industrial lighting
- LED back-up lighting
- Illuminated sign

Quick Start



Recommended Equipment

- 60VDC Power supply
- 3 pcs of LED panel (1W LED, 10 LEDs in series on each panel)
- Multi-meter

Recommended Input and Output Ratings

- Input: 6-40VDC
 - Output: 1-10 LEDs in series/333mA
- Note: The input voltage must be 2V higher than the output voltage (total Vf).

Absolute Maximum Ratings

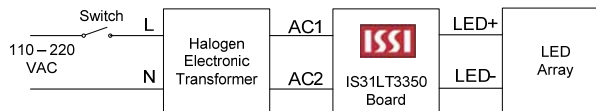
- Input voltage \leq 40VDC

Caution: Do not exceed the conditions listed above, otherwise the board will be damaged.

Procedure

The IS31LT3350 Evaluation Board is fully assembled and tested. Follow the steps listed below to verify board operation.

Caution: Do not turn on the power supply until all connections are completed.



- 1) Connect the terminals of the power supply to the AC1 and AC2 pin (If the board don't have the rectifier(D1-D4), Connect the positive terminal of the power supply to the VCC of the board and the negative terminal of power supply to the GND of the board) .
- 2) Connect the negative of the one of LED panel (LED arrays) to the LED1- terminal. And connect the positive of the same LED panel (LED arrays) to the LED1+ terminal.
- 3) Connect the other two LED panels to LED2 and LED3 as above.
- 4) Turn on the power supply and the LED panels (LED arrays) will be light.

Ordering Information

PART #	TEMP RANGE	IC PACKAGE
IS31LT3350-V1SDLS2-EB3CH	-40 °C to 105°C	SOT23-5 (5.0x6.0mm)

For pricing, delivery, and ordering information, please contact ISSI at analog_mkt@issi.com or call +1-408-969-6600

Detailed Description

LED Current Control

The nominal average output current in the LED(s) is determined by the value of the external current sense resistor (R_S) connected between V_{IN} and I_{SENSE} and is given by:

$$I_{OUT\ nom} = 0.1/R_S \text{ [for } R_S > 0.13\Omega \text{]}$$

The table below gives values of nominal average output current for several preferred values of current setting resistor (R_S) in the typical application circuit shown on page 1:

R_S (Ω)	Nominal average output current (mA)
0.13	769
0.15	667
0.27	370
0.3	333

V_{sense} is divided into two range to improve current accuracy, please refer to bin information on page 3. The above values assume that the ADJ pin is floating and at a nominal voltage of $V_{REF} = 1.2V$.

Note that $R_S = 0.13\Omega$ is the minimum allowed value of sense resistor under these conditions to maintain switch current below the specified maximum value. It is possible to use different values of R_S if the ADJ pin is driven from an external voltage.

Inductor selection

Recommended inductor values are in the range $47\mu H$ to $220\mu H$.

Higher values of inductance are recommended at higher supply voltages and low output current in order to minimize errors due to switching delays, which result

in increased ripple and lower efficiency. Higher values of inductance also result in a smaller change in output current over the supply voltage range. The inductor should be mounted as close to LX pin as possible with low resistance connections to LX and V_{IN} pins.

PCB layout consideration

Decoupling capacitors and coil

It is particularly important to mount the coil and the input decoupling capacitor close to the chip to minimize parasitic resistance and inductance, which will degrade efficiency. The input decoupling capacitor ($0.1\mu F$ fixed) must be placed as close to the V_{in} and GND pins as possible. It is also important to take account of any trace resistance in series with current sense resistor R_S .

LX pin

The LX pin of the chip is a fast switching node, so PCB traces should be kept as short as possible. To minimize ground 'bounce', the ground pin of the chip should be soldered directly to the ground plane.

ADJ pin

The ADJ pin is a high impedance input, so when left floating, PCB traces to this pin should be as short as possible to reduce noise pickup. ADJ pin can also be connected to a voltage between $1.2V \sim 5V$. In this case, the internal circuit will clamp the output current at the value which is set by $ADJ = 1.2V$.

High voltage traces

Avoid running any high voltage traces close to the ADJ pin, to reduce the risk of leakage due to board contamination. Any such leakage may raise the ADJ pin voltage and cause excessive output current. A ground ring placed around the ADJ pin will minimize changes in output current under these conditions.

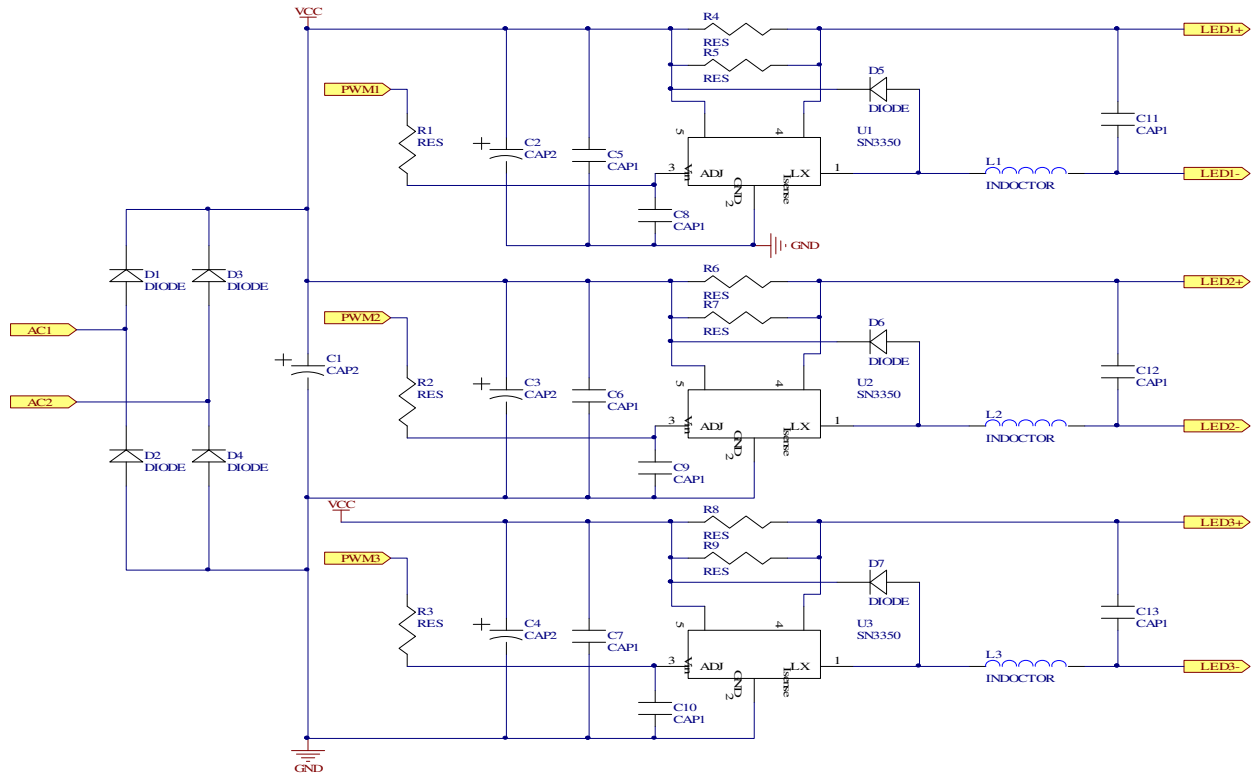


Figure 1 IS31LT3350 3CH Evaluation Board Schematic

Bill of Materials

No.	Name	Description	Ref Des.	Qty.	Mfr
1	AL Capacitor	220uF,50V	C1	1	
2	AL Capacitor	100uF,50V	C2,C3,C4	3	
2	SMD Capacitor	100nF,50V	C5,C6,C7	3	
3	SMD Capacitor	10nF,50V	C8,C9,C10	3	
4	SMD Capacitor	1uF,50V	C11,C12,C13	3	
5	SMD Resistor	1KΩ±5%,0805	R4,R6,R8	3	
6	SMD Resistor	0.3Ω±1%,0805	R4,R6,R8	3	
7	Schottky Diode	SS26,2A,60V	D1-D7	7	
8	SMD Inductor	47uH,Isat≥600A	L1,L2,L3	3	
9	IC	IS31LT3350,SOT89-5	U1,U2,U3	3	

Note: C8,C9, C10 is the optional components. They can filter the noise coupling to the ADJ pin.

PCB Layout

NOTE: Physical dimensions are (L x W x H): 58mm x 25mm x 22mm

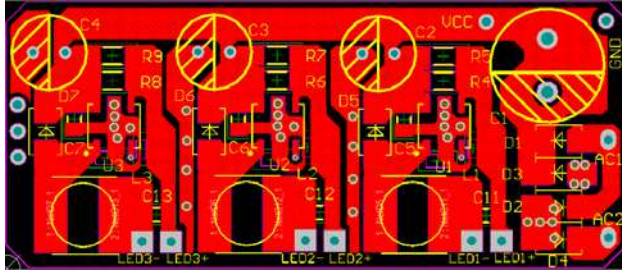


Figure 2 PCB Layout-Top Layer

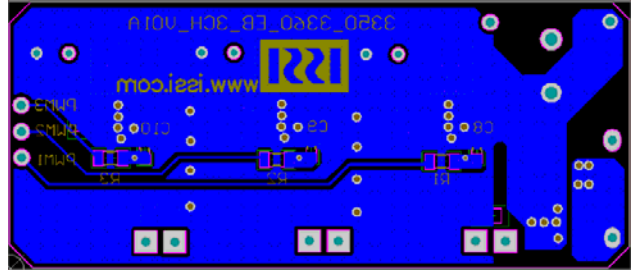


Figure 3 PCB Layout-Bottom Layer

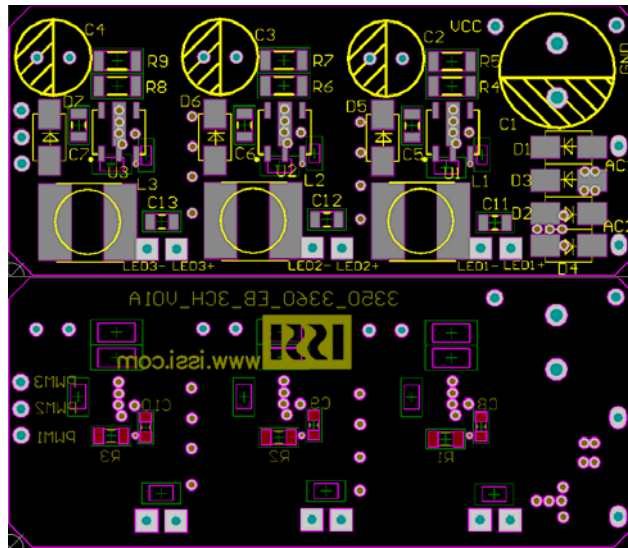


Figure 4 Component Placement Guide -Top Layer

Figure 5 Component Placement Guide -Bottom Layer

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